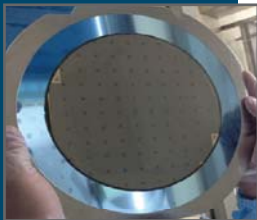
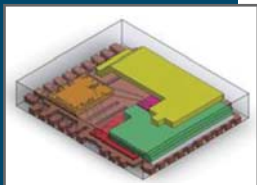
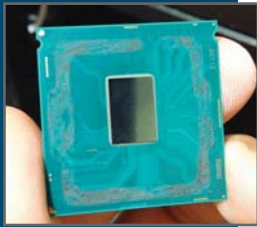


# Advanced Packaging Update: Market and Technology Trends

Vol. 4-0916



The Advanced Packaging Update (4-0916) features special coverage of the market with a forecast for units of BGAs and CSPs by package construction. The CSP market is divided into laminate and leadframe (QFN) substrates. Details of stacked die CSPs and stacked package constructions are provided. Package-on-package (PoP) trends and growth projections are included. Estimates of the market for each package type are based on input from captive as well as merchant assembly operations. Key applications and drivers for unit volume growth are highlighted. A special section is devoted to the growth of the China domestic OSAT market. An economic analysis examines macroeconomic trends and their impact on the semiconductor packaging and assembly industry.

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